TOSHIBA

Discrete Semiconductors

2SK2038

Unit in mm

Field Effect Transistor

Silicon N Channel MOS Type (t-MOS II.5)

High Speed, High Current Switching Applications

Features

- Low Drain-Source ON Resistance
- R_{DS(ON)} = 1.8Ω (Typ.) High Forward Transfer Admittance
 - $|Y_{fs}| = 3.0S$ (Typ.)
- Low Leakage Current
 - $I_{DSS} = -300\mu A \text{ (Max.)} @ V_{DS} = 640V$
- Enhancement-Mode
 - $V_{th} = 1.5 \sim 3.5 V @ V_{DS} = -10 V$, $V_{DS} = 1 mA$

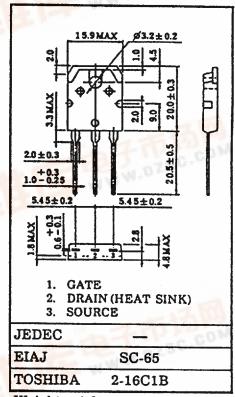
Absolute Maximum Ratings (Ta = 25C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Drain-Source Voltage		V _{DSS}	800	٧	
Drain-Gate Voltage (R _S = 20kΩ)		V _{DGR}	800	٧	
Gate-Source Voltage		Vass	±30	٧	
Drain Current	DC	Ь	5	Α	
	Pulse	I _{DP}	15		
Drain Power Dissipation (Tc = 25°C)		P _D	125	W	
Channel Temperature		En	150	°C	
Storage Temperature Range		Jig .	-55 ~ 150	°C	

Thermal Characteristics

CHARACTERISTIC	SYMBOL	MAX.	UNIT	
Thermal Resistance, Channel to Case	fi(ch-c)	1.0	°C/W	
Thermal Resistance, Channel to Ambient	R)(ch-a)	50	°C/W	

This transister is an electrostatic sensitive device. Please handle with caution.



Weight: 4.6g



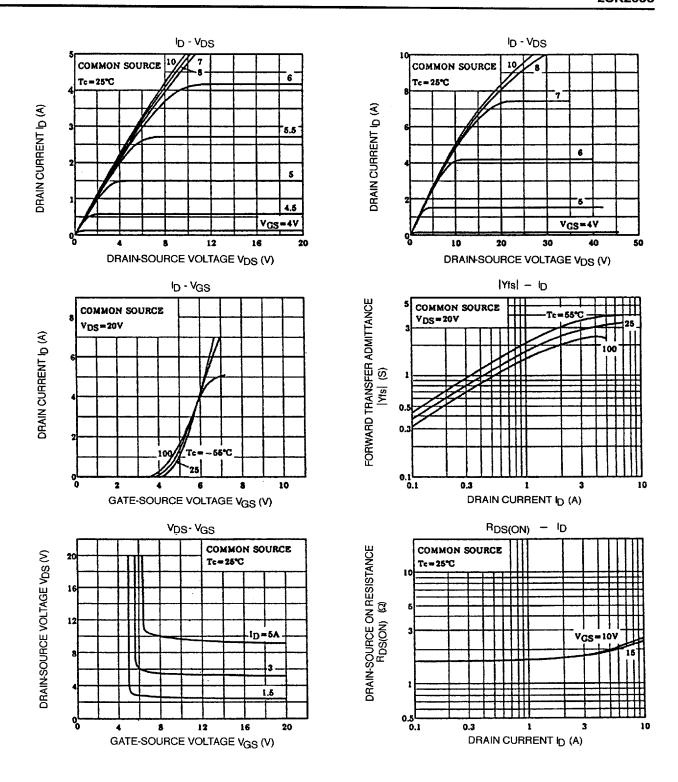
Electrical Characteristics (Ta = 25C)

CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Sate Leakage Current 6SS V _{GS} = ±30V, V		$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA	
Drain Cut-off Current Drain-Source Breakdown Voltage		I _{DSS}	I _{DSS} V _{DS} = 640V, V _{GS} = 0V		-	300	μA
		(6R) DSS ID = 10mA, VGS = 0V	800	-	-	٧	
Gate Threshold Voltage		₩.	V _{DS} = 10V, I _D = -1mA	1.5	_	3.5	٧
Drain-Source ON	Resistance	Pos (ON)	V _{GS} = 10V, b = 3A		1.8	2.2	Ω
Forward Transfer	Admittance	Y _{fs} I	V _{DS} = 20V, b = 3A	1.0	3.0	-	S
Input Capacitance Reverse Transfer Capacitance Output Capacitance		Gss	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz	-	610	870	ρF
		Çss		-	60	100	
		Coss		_	110	165	
Switching Time	Rise Time	tr	VGS RL=66.7Ω		30	60	ns
	Turn-on Time	b n			70	140	
-	Fall Time	1		-	35	70	
	Turn-off Time	Pu	V _{IN} : t _r , t _f <5ns, V _{DD} =200V Duty≤1%, t _w =10µs	-	165	330	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Qg	V _{DD} = 400V, V _{GS} = 10V,	-	47	94	
Gate-Source Charge		Q _s	{ ID = -5A	-	19	-	nC
Gate-Drain ("Mill	er") Charge	Q d		-	28	-	

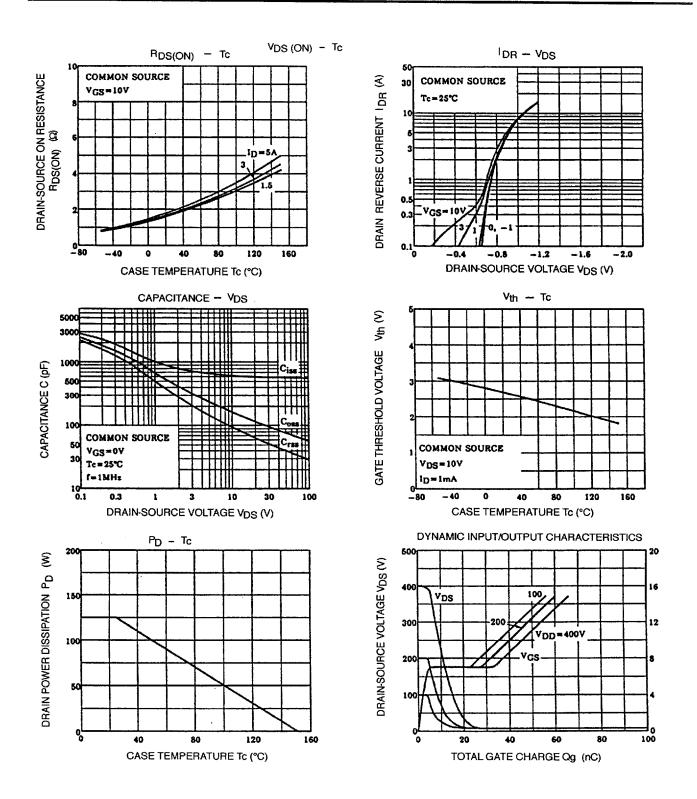
Source-Drain Diode Ratings and Characteristics (Ta = 250)

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	dr		-	_	5	Α
Pulse Drain Reverse Current	O RP	_		-	15	Α
Diode Forward Voltage	Yosf	I _{DR} = 5A, V _{GS} = 0V	_		-1.9	٧
Reverse Recovery Time	4	I _{DR} = 5A, V _{GS} = 0V	-	1450	- 1	ns
Reverse Recovered Charge	Q,	dl _{DR} / _{dt} = 100A/µs	-	20	-	μC

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